

1 Description

The iW1699B is a high performance AC/DC power supply controller that uses digital control technology to build peak current mode PWM flyback power supplies. The device operates in quasi-resonant mode to provide high efficiency along with a number of key built-in protection features while minimizing the external component count, simplifying EMI design and lowering the total bill of material cost. The iW1699B removes the need for secondary feedback circuit while achieving excellent line and load regulation. It also eliminates the need for loop compensation components while maintaining stability over all operating conditions. Pulse-by-pulse waveform analysis allows for a loop response that is much faster than traditional solutions, resulting in improved dynamic load response. The built-in power limit func



faster than traditional solutions, resulting in improved dynamic load response. The built-in power limit function enables optimized transformer design in universal off-line applications and allows for a wide input voltage range.

Dialog's innovative proprietary technology ensures that power supplies built with the iW1699B can achieve both the highest average active efficiency and less than 30mW no-load power consumption, and have fast dynamic load response in a compact form factor in typical 5V, 2.4A 12W applications. The active start-up scheme enables the shortest possible start-up time without sacrificing no-load power loss.

2 Features

- No-load power consumption < 30mW at 230V_{AC} along with fast dynamic load response and short turn-on delay in typical 5V, 2.4A 12W compact adapter/charger applications
- Tight constant-voltage and constant current regulation across line and load range
- Primary-side feedback eliminates opto-isolators and simplifies design
- Intelligent low power management achieves ultra-low operating current (~250µA) at no-load
- Proprietary optimized 89kHz maximum PWM switching frequency with quasi-resonant operation achieves best size, efficiency and common mode noise
- User-configurable 5-level cable drop compensation provides design flexibility
- **EZ-EMI®** design enhances manufacturability

3 Applications

- Compact AC/DC adapters or chargers for media tablets and smart phones
- AC/DC adapters for consumer electronics

- Adaptive multi-mode PWM/PFM control improves efficiency
- Complies with DoE External Power Supply and EU CoC Version 5, Tier 2 standards
- Built-in single-point fault protections against output short-circuit, output over-voltage and output overcurrent
- Dedicated pins for external over-temperature protection and over-voltage protection, with latch function available
- **SmartDefender**[™] smart hiccup technology helps to address issues of soft shorts in cables and connectors by effectively reducing the average output power at fault conditions without latch
- Optional on-chip internal over-temperature protection
- No audible noise over entire operating range





Figure 3.1 : iW1699B Typical Application Circuit (Using Depletion Mode N-FET as Active Start-up Device) (Achieving < 30mW No-load Power Consumption in 5V, 2.4A 12W Adapter Designs)



Figure 3.2 : iW1699B Typical Application Circuit (Alternative Circuit without Using Active Start-up Device)

Note: Pin 4 (ASU) can be left unconnected if an active start-up device is not needed in the application circuit.

Product	Summary
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4 Pinout Description

iW1699B 1 V_{SENSE} V_{CC} 8 2 SD GND 7 3 CFG OUTPUT 6 4 ASU I_{SENSE} 5

Figure 4.1 : 8 Lead SOIC-8 Package

Pin Number	Pin Name	Туре	Pin Description
1	V _{SENSE}	Analog Input	Auxiliary voltage sense. Used for primary side regulation.
2	SD	Analog Input	External shutdown control. Can be configured for external over-temperature protection (OTP) by connecting an NTC resistor from this pin to Ground.
3	CFG	Analog Input	Used for external cable drop compensation (CDC) configuration and supplemental over-voltage protection (OVP).
4	ASU	Output	Control signal. Used for active start-up device (BJT or depletion mode NFET).
5	I _{SENSE}	Analog Input	Primary current sense. Used for cycle-by-cycle peak current control and limit.
6	OUTPUT	Output	Gate drive for external MOSFET switch.
7	GND	Ground	Ground.
8	V _{cc}	Power Input	IC power supply.

5 Absolute Maximum Ratings Absolute maximum ratings are the parameter values or ranges which can cause permanent damage if exceeded. For maximum safe operating conditions, refer to Electrical Characteristics in Section 6.

Parameter	Symbol	Value	Units
DC supply voltage range (pin 8, I _{CC} = 20mA max)	V _{cc}	-0.3 to 25.0	V
Continuous DC supply current at V_{CC} pin (V_{CC} = 15V)	I _{cc}	20	mA
ASU output (pin 4)		-0.3 to 19.0	V
OUTPUT (pin 6)		-0.3 to 20.0	V
V _{SENSE} input (pin 1, I _{Vsense} ≤ 10mA)		-0.7 to 4.0	V
I _{SENSE} input (pin 5)		-0.3 to 4.0	V
SD (pin 2)		-0.3 to 4.0	V
CFG (pin 3, I _{CFG} ≤ 20mA)		-0.8 to 4.0	V
Maximum junction temperature	T _{JMAX}	150	°C
Operating junction temperature	T _{JOPT}	-40 to 150	°C
Storage temperature	T _{STG}	-65 to 150	°C
Thermal resistance junction-to-ambient	θ _{JA}	160	°C/W
ESD rating per JEDEC JESD22-A114		±2,000	V
Latch-up test per JESD78A		±100	mA



6 Physical Dimensions

8-Lead Small Outline (SOIC) Package



Symbol	Inc	hes	Millim	neters
Syr	MIN	MAX	MIN	MAX
А	0.061	0.068	1.55	1.73
A1	0.0040	0.0098	0.127	0.250
A2	0.055	0.061	1.40	1.55
В	0.0138	0.0192	0.35	0.49
С	0.0075	0.0098	0.19	0.25
D	0.189	0.196	4.80	4.96
Е	0.150	0.157	3.81	3.99
е	0.050) BSC	1.27	BSC
Н	0.230	0.244	5.84	6.20
h	0.10	0.016	0.25	0.41
L	0.016	0.040	0.4	1.0
α	0°	8°		

Compliant to JEDEC Standard MS12F

Controlling dimensions are in inches; millimeter dimensions are for reference only

This product is RoHS compliant and Halide free.

Soldering Temperature Resistance:

[a] Package is IPC/JEDEC Std 020D Moisture Sensitivity Level 1

[b] Package exceeds JEDEC Std No. 22-A111 for Solder Immersion Resistance; package can withstand 10 s immersion < 270°C</p>

Dimension D does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.25 mm per side. D and E1 dimensions are determined at datum H.

The package top may be smaller than the package bottom. Dimensions D and E1 are determined at the outermost extremes of the plastic bocy exclusive of mold flash, tie bar burrs, gate burrs and interlead flash, but including any mismatch between the top and bottom of the plastic body.

7 Ordering Information

Part No.	Options	Package	Description
iW1699B-02	No OVP/OTP latch, 0.75V shutdown voltage, no smart hiccup	SOIC-8	Tape & Reel ¹
iW1699B-03	OVP/external OTP latch, 0.75V shutdown voltage, no smart hiccup	SOIC-8	Tape & Reel ¹
iW1699B-05	No OVP/OTP latch, 3V CC shutdown voltage, no smart hiccup	SOIC-8	Tape & Reel ¹
iW1699B-06	No OVP/OTP latch, 3V CC shutdown voltage, smart hiccup with 3/8 duty cycle	SOIC-8	Tape & Reel ¹
iW1699B-15	No OVP/OTP latch, 3V CC shutdown voltage, no smart hiccup, no internal OTP	SOIC-8	Tape & Reel ¹

Note 1: Tape & Reel packing quantity is 2,500/reel. Minimum ordering quantity is 2,500.

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Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu Koto-ku, Tokyo 135-0061, Japan www.renesas.com

Contact Information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit: www.renesas.com/contact/

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